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United States Patent [19]
Ishii

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[54] HEAT RETAINING TUBE FOR USE IN A SEMICONDUCTOR WAFER HEAT PROCESSING APPARATUS

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[73] Assignee: Tokyo Electron Limited, Tokyo-to, Japan

[**] Term: 14 Years

[21] Appl. No.: 74,278

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[30] Foreign Application Priority Data

Jan. 31, 1997	[JP]	Japan	9-2649
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[51] LOC (6) Cl. 13-03

[52] U.S. Cl. D13/182

[58] Field of Search D13/182, 144, D13/144.1, 199, 179; 414/935-941, 217, 147; 437/247, 946

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Primary Examiner—Brian N. Vinson
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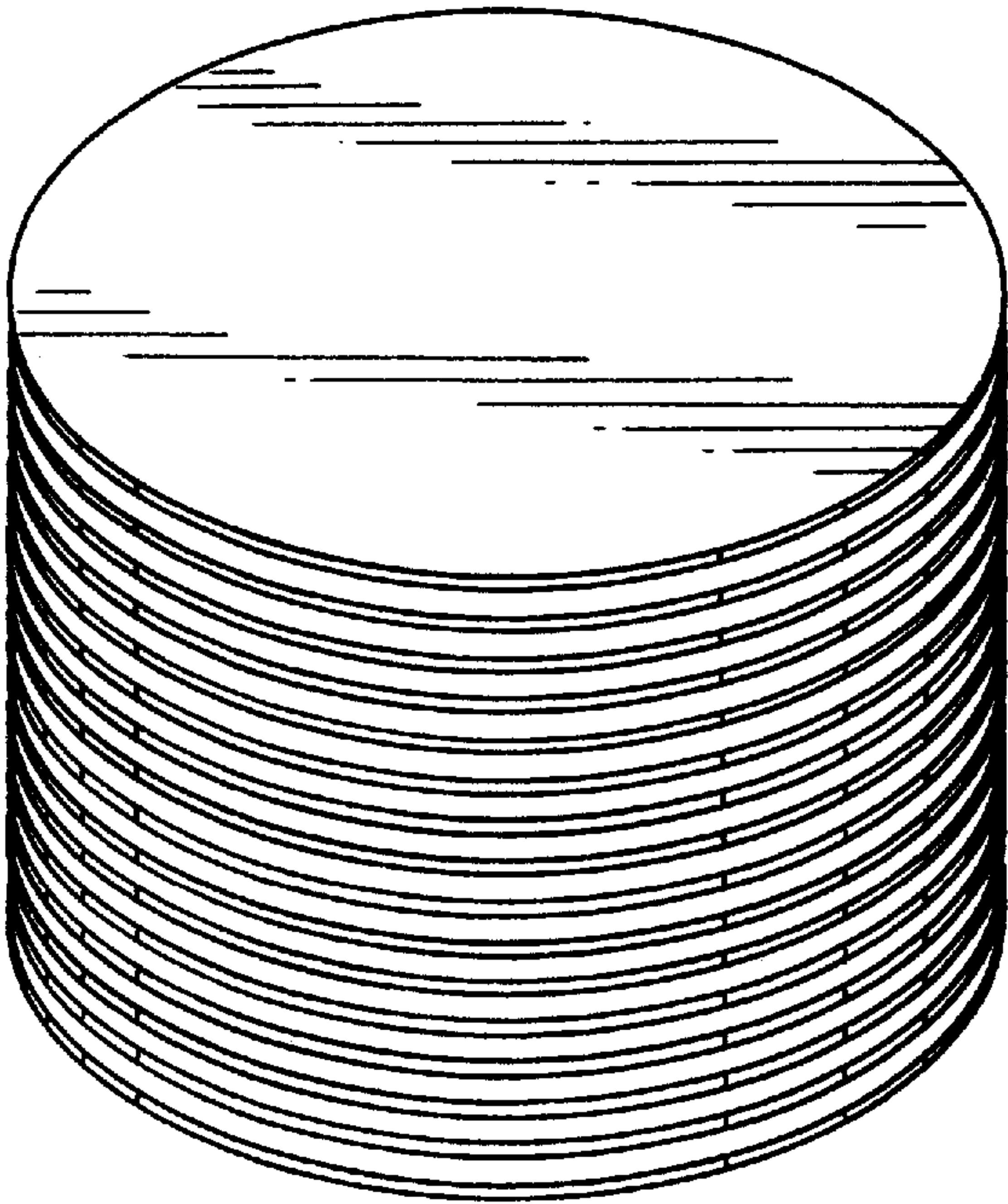
[57] CLAIM

I claim the ornamental design for a heat retaining tube for use in a semiconductor wafer heat processing apparatus, as shown and described.

DESCRIPTION

FIG. 1: a perspective view of a heat retaining tube for use in a semiconductor wafer heat processing apparatus;
FIG. 2: a top plan view thereof;
FIG. 3: a front elevational view thereof, the rear elevational view is identical with the front view;
FIG. 4: a right side view thereof, the left side view being a mirror image of the right view;
FIG. 5: a bottom plan view thereof; and,
FIG. 6: a cross sectional view thereof taken along line VI—VI in FIG. 3.

1 Claim, 2 Drawing Sheets



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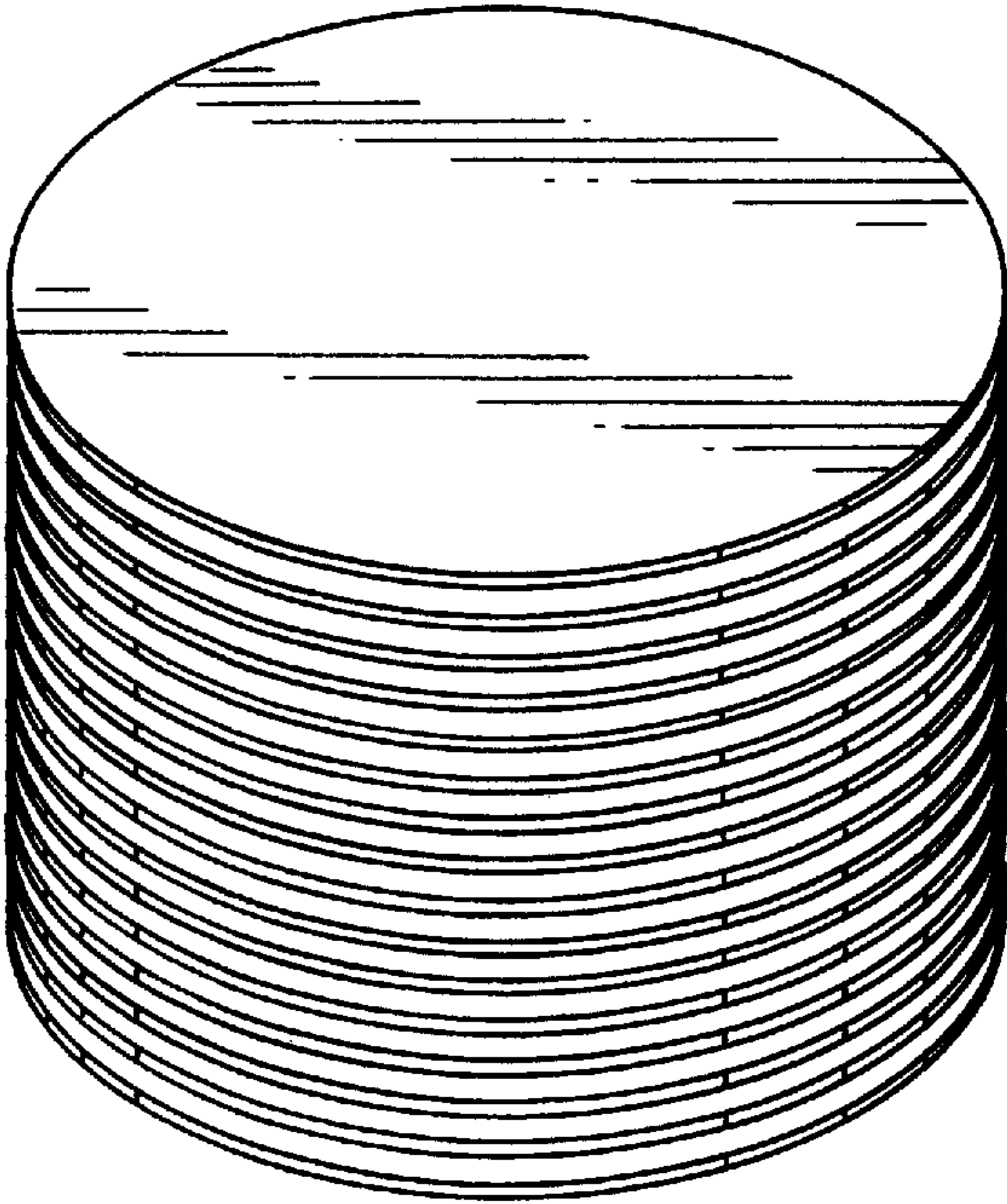


FIG. 2

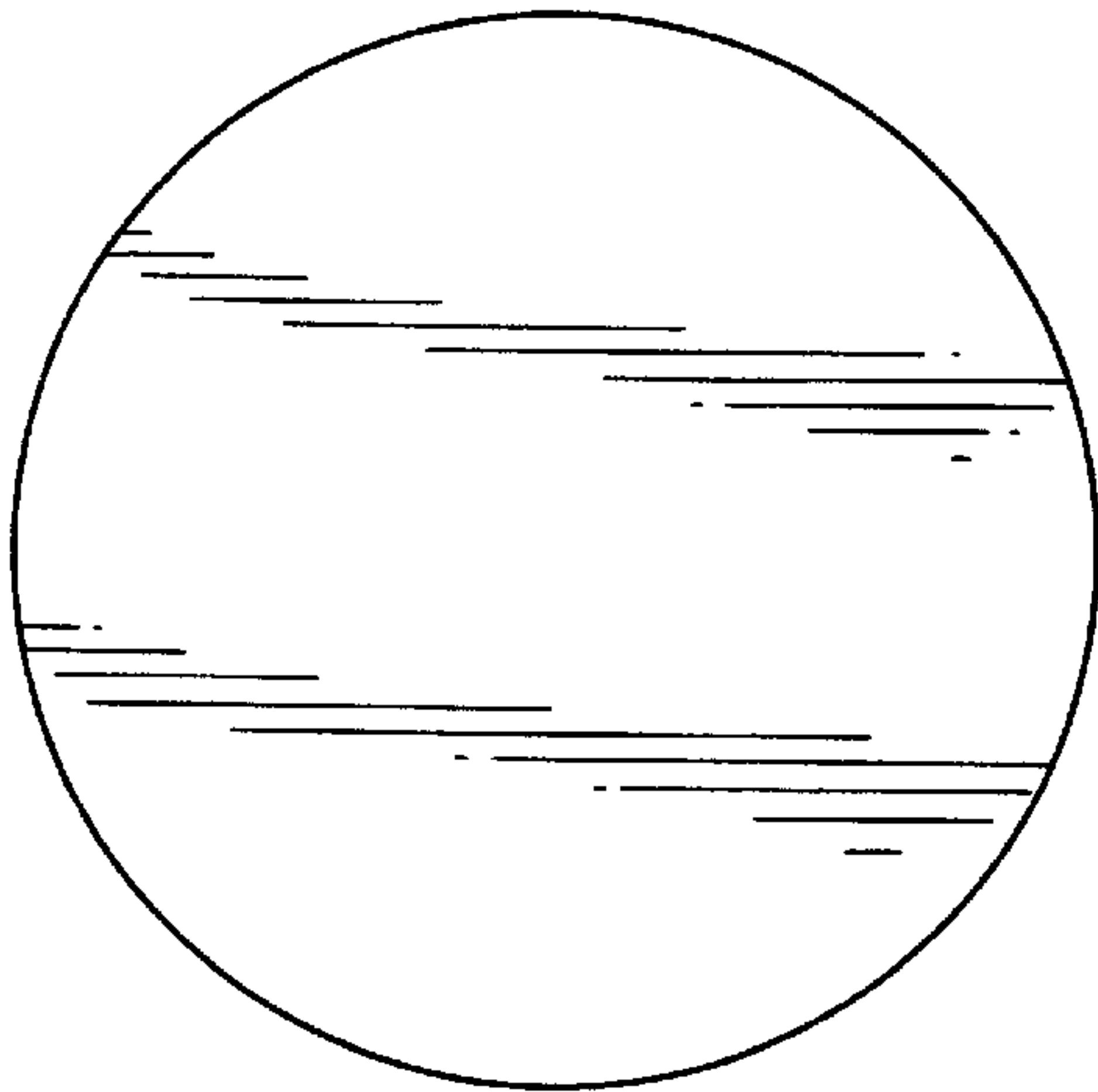


FIG. 4

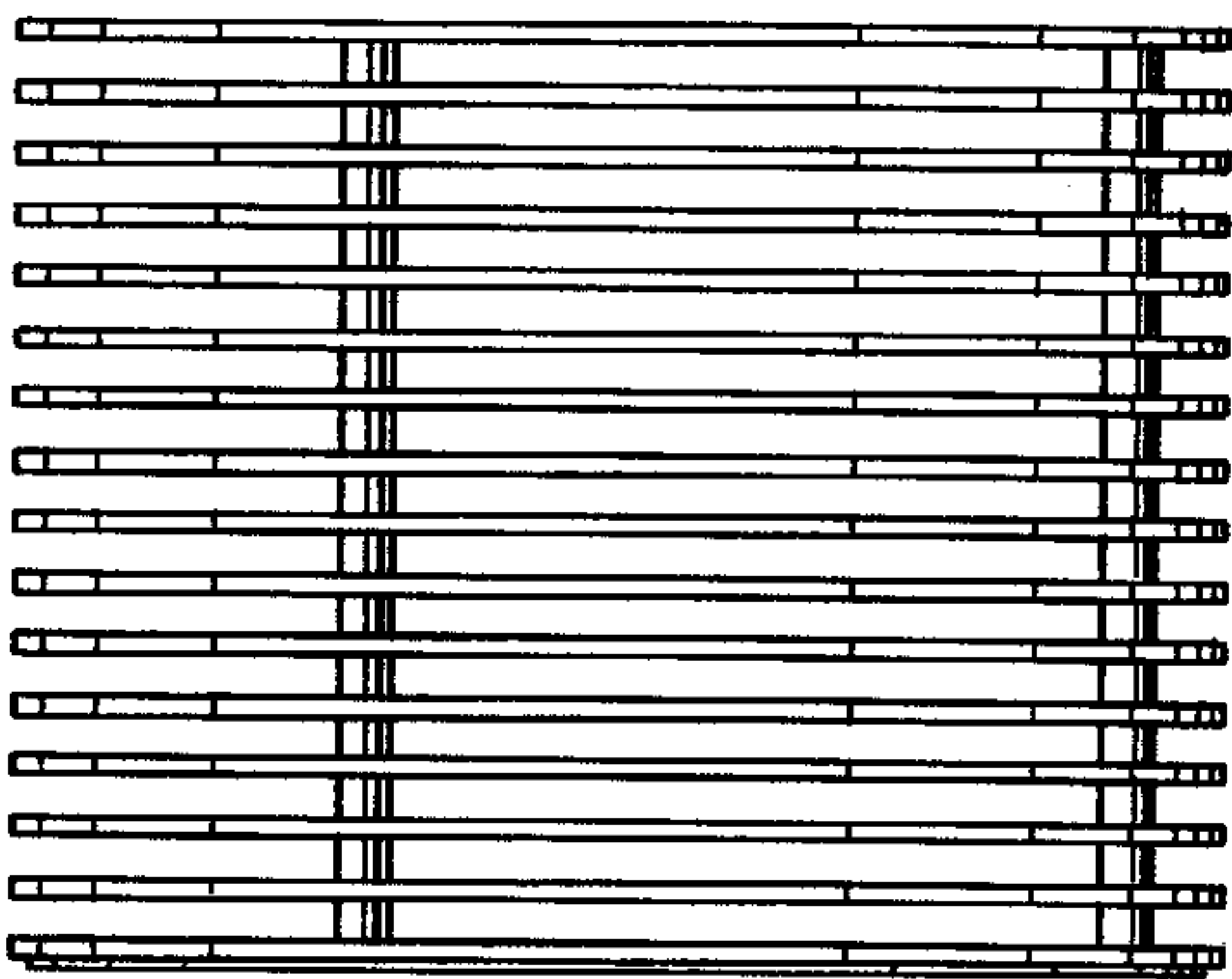


FIG. 3

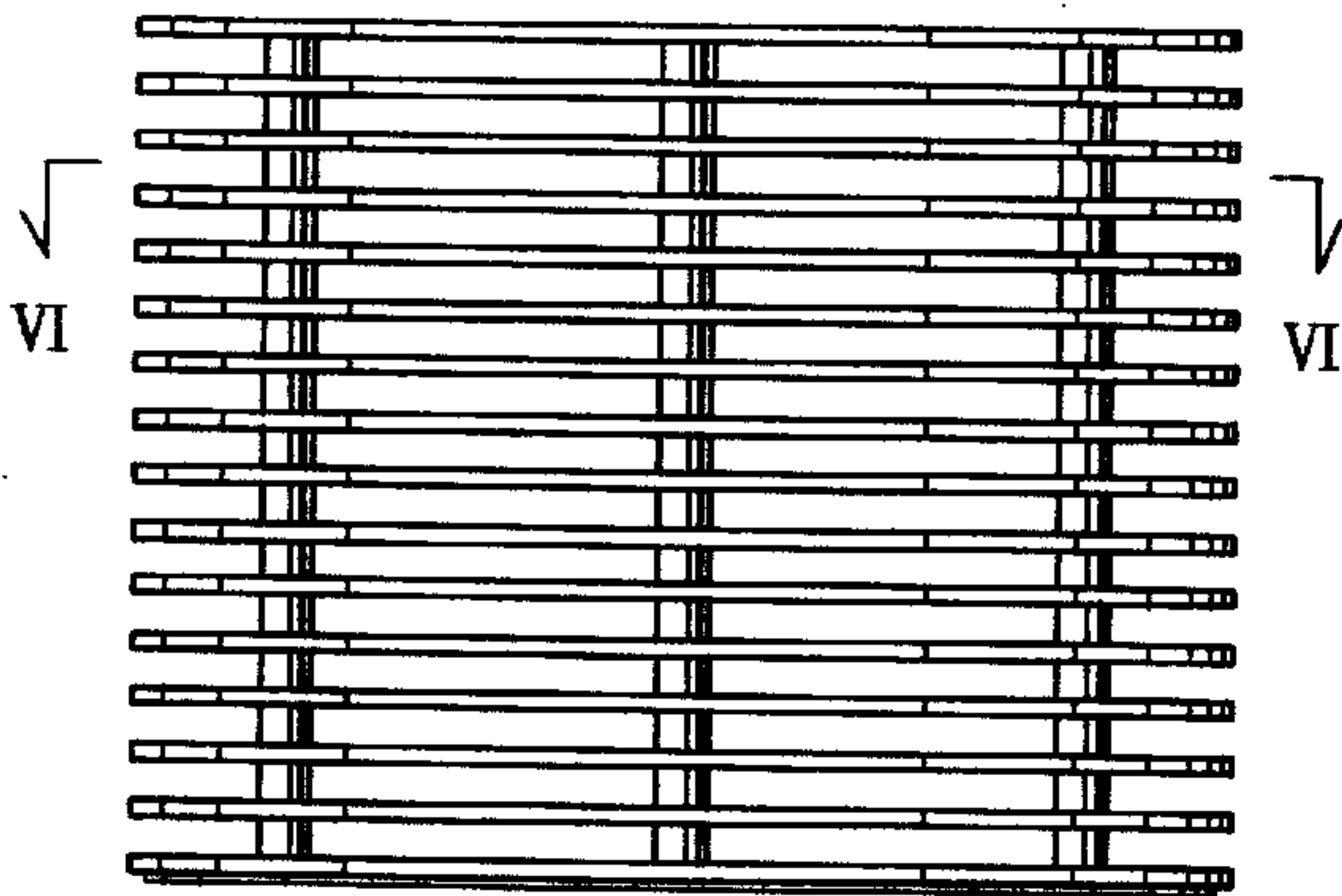


FIG. 6

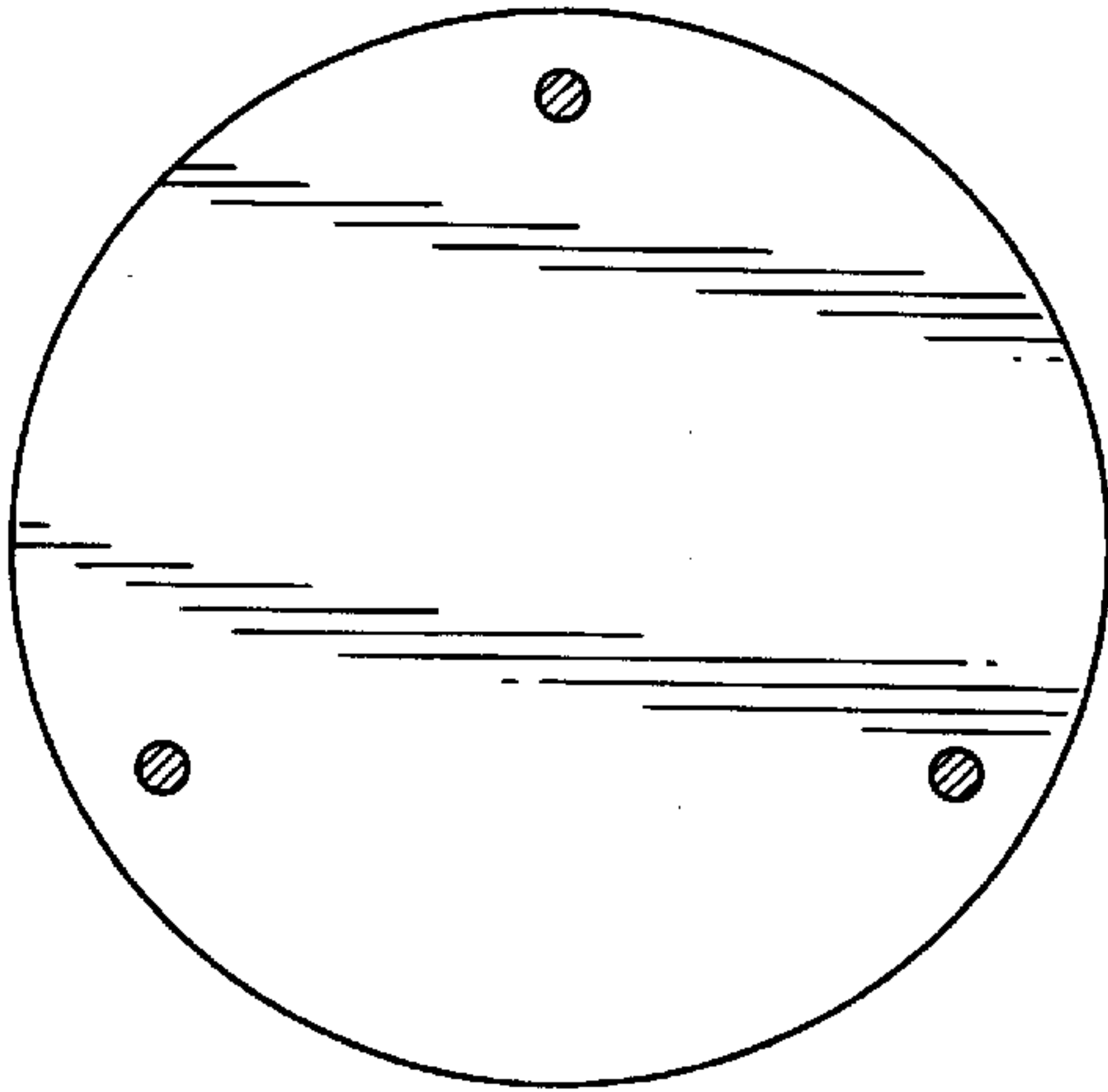


FIG. 5

